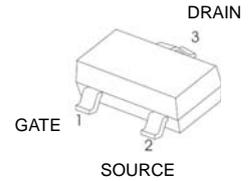
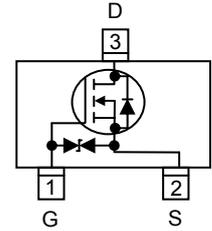




## MT2021W Plastic-Encapsulate MOSFETS

N-Channel, 20V, 0.89A, Small Signal MOSFET

$V_{DS}$ (V)	$R_{ds(on)}$ ( $\Omega$ )	$I_D$ (A)
20	0.220@ $V_{GS}=4.5V$	0.55
	0.260@ $V_{GS}=2.5V$	0.45
	0.320@ $V_{GS}=1.8V$	0.35



**SOT-323**

### Descriptions

The MT2021W is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion, load switch and level shift. Standard Product MT2021W is Pb-free.

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage

### Applications

- DC-DC converter circuit
- Small Signal Switch
- Load Switch
- Level Shift

**Marking :** 21



## Absolute Maximum ratings

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	20		V
Gate-Source Voltage		$V_{GS}$	$\pm 6$		
Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}\text{C}$	$I_D$	0.89	0.82	A
	$T_A=70^{\circ}\text{C}$		0.71	0.65	
Maximum Power Dissipation <sup>a</sup>	$T_A=25^{\circ}\text{C}$	$P_D$	0.37	0.31	W
	$T_A=70^{\circ}\text{C}$		0.23	0.20	
Continuous Drain Current <sup>b</sup>	$T_A=25^{\circ}\text{C}$	$I_D$	0.78	0.70	A
	$T_A=70^{\circ}\text{C}$		0.62	0.56	
Maximum Power Dissipation <sup>b</sup>	$T_A=25^{\circ}\text{C}$	$P_D$	0.29	0.23	W
	$T_A=70^{\circ}\text{C}$		0.18	0.14	
Pulsed Drain Current <sup>c</sup>		$I_{DM}$	1.4		A
Operating Junction Temperature		$T_J$	150		$^{\circ}\text{C}$
Lead Temperature		$T_L$	260		$^{\circ}\text{C}$
Storage Temperature Range		$T_{stg}$	-55 to 150		$^{\circ}\text{C}$

## Thermal resistance ratings

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	275	335	$^{\circ}\text{C/W}$
	Steady State		325	395	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	375	430	
	Steady State		445	535	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	260	300	

a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

b Surface mounted on FR4 board using minimum pad size, 1oz copper

c Repetitive rating, pulse width limited by junction temperature,  $t_p=10\mu\text{s}$ , Duty Cycle=1%

d Repetitive rating, pulse width limited by junction temperature  $T_J=150^{\circ}\text{C}$ .

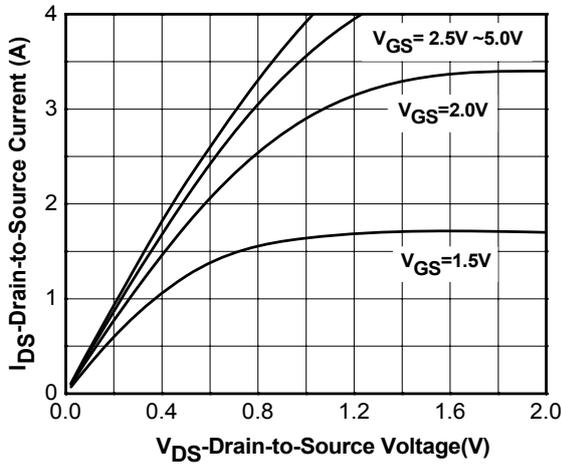


## Electronics Characteristics (Ta=25°C, unless otherwise noted)

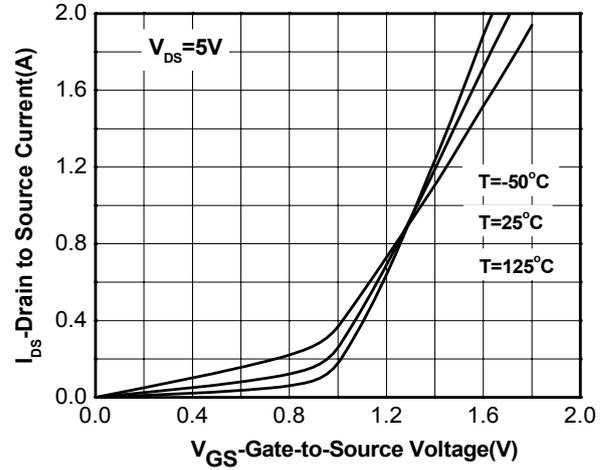
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0V			100	nA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±5V			5	uA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	0.45	0.58	0.85	V
Drain-to-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.55A		220	260	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 0.45A		260	310	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 0.35A		320	380	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 0.55A		2.0		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 10 V		50		pF
Output Capacitance	C <sub>OSS</sub>			13		
Reverse Transfer Capacitance	C <sub>RSS</sub>			8		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.55A		1.15		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.06		
Gate-to-Source Charge	Q <sub>GS</sub>			0.15		
Gate-to-Drain Charge	Q <sub>GD</sub>			0.23		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10V, R <sub>L</sub> = 3 Ω, R <sub>G</sub> = 6 Ω		22		ns
Rise Time	tr			80		
Turn-Off Delay Time	td(OFF)			700		
Fall Time	tf			380		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.35A	0.5	0.7	1.1	V



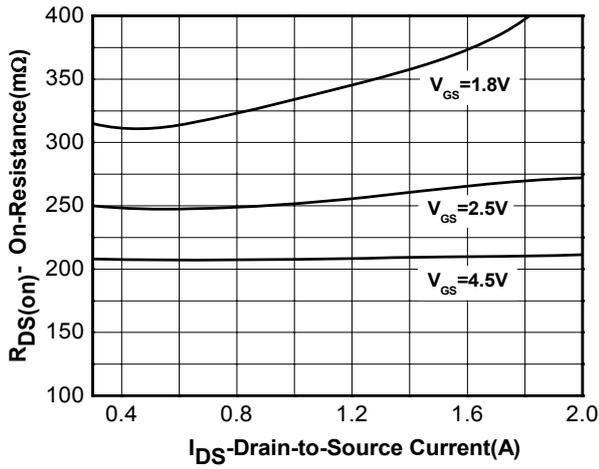
### Typical Characteristics (Ta=25°C, unless otherwise noted)



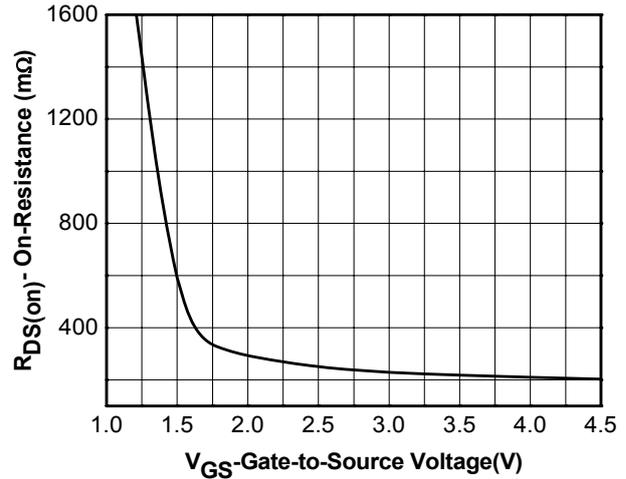
Output characteristics



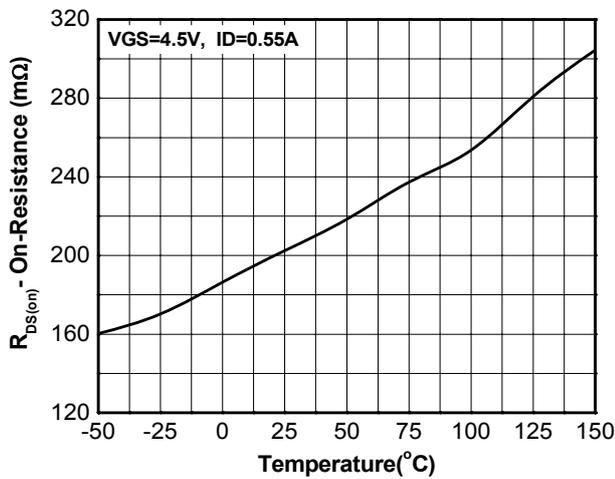
Transfer characteristics



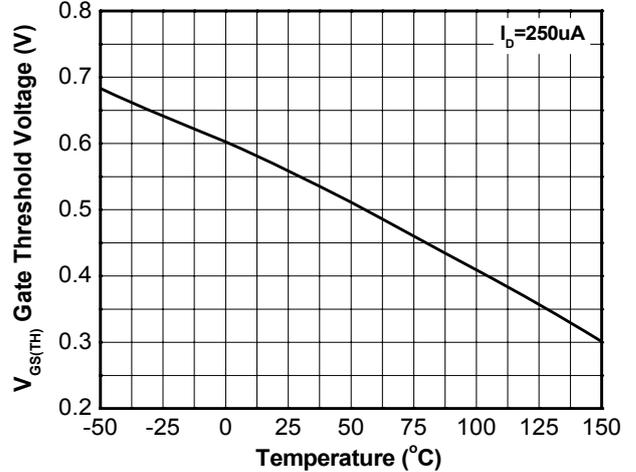
On-Resistance vs. Drain current



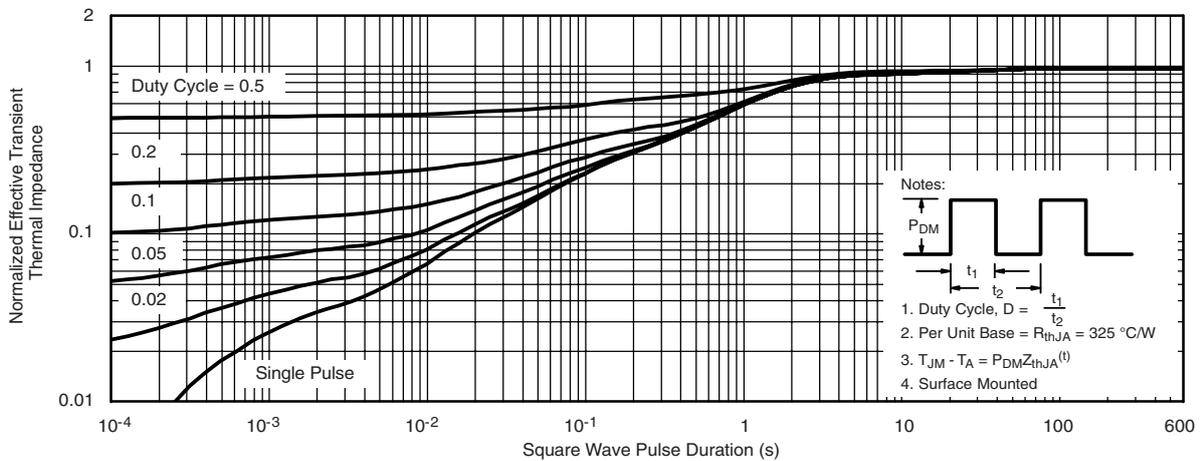
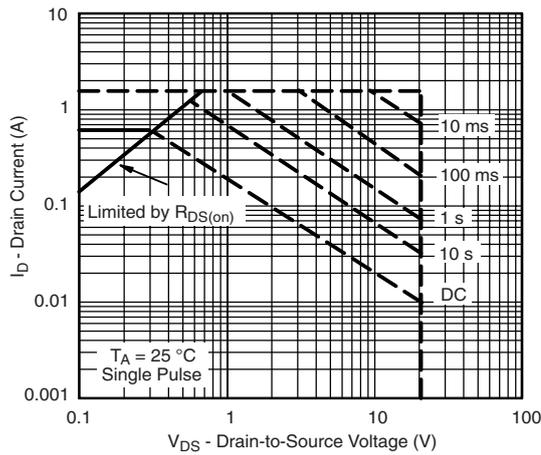
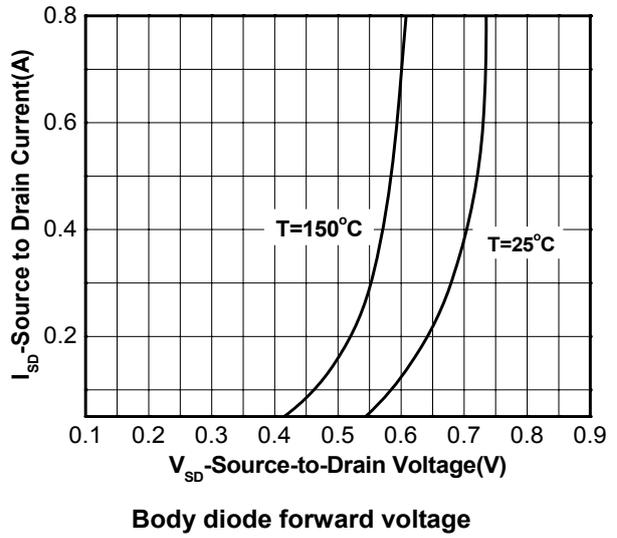
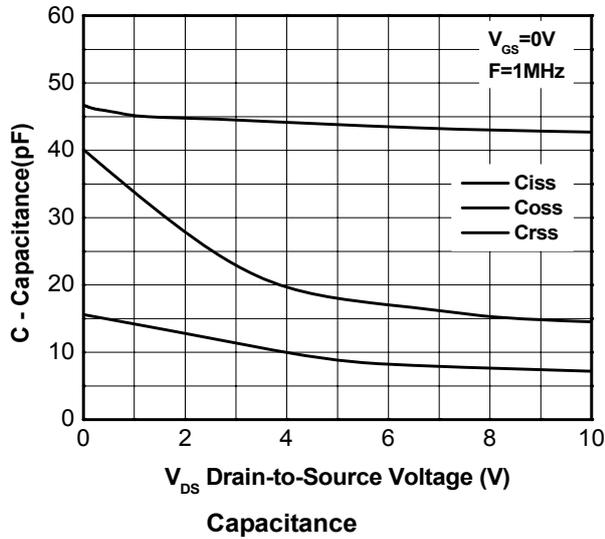
On-Resistance vs. Gate-to-Source voltage



On-Resistance vs. Junction temperature



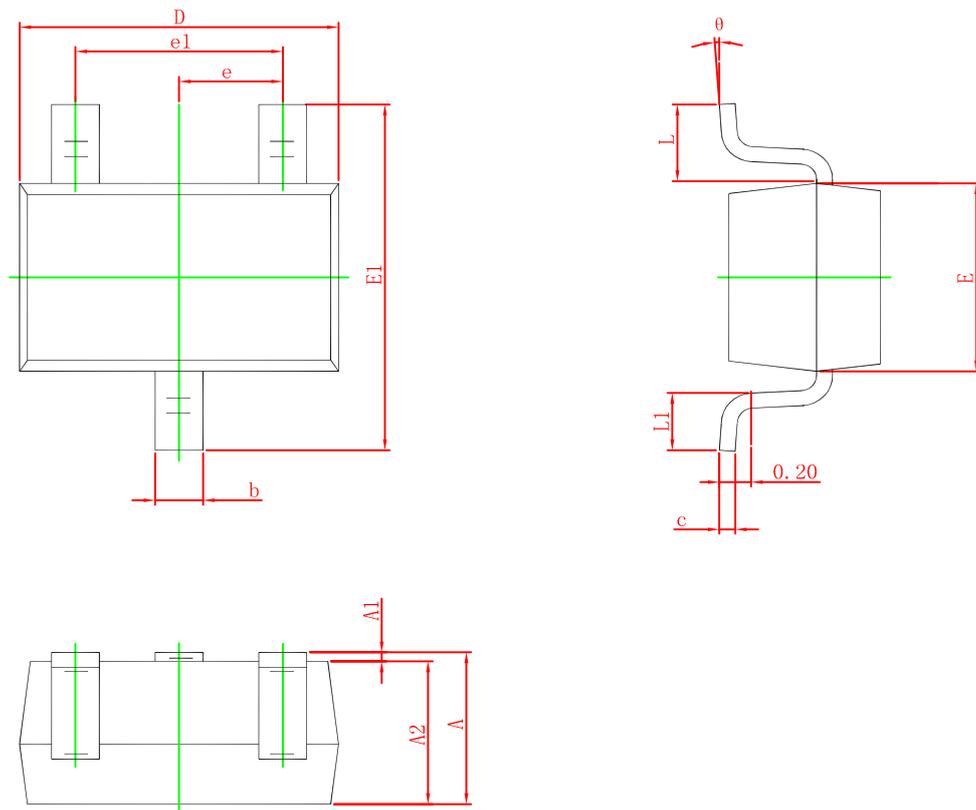
Threshold voltage vs. Temperature



Transient thermal response (Junction-to-Ambient)



## SOT-323 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.525 REF.		0.021 REF.	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°